FAB NOTES:

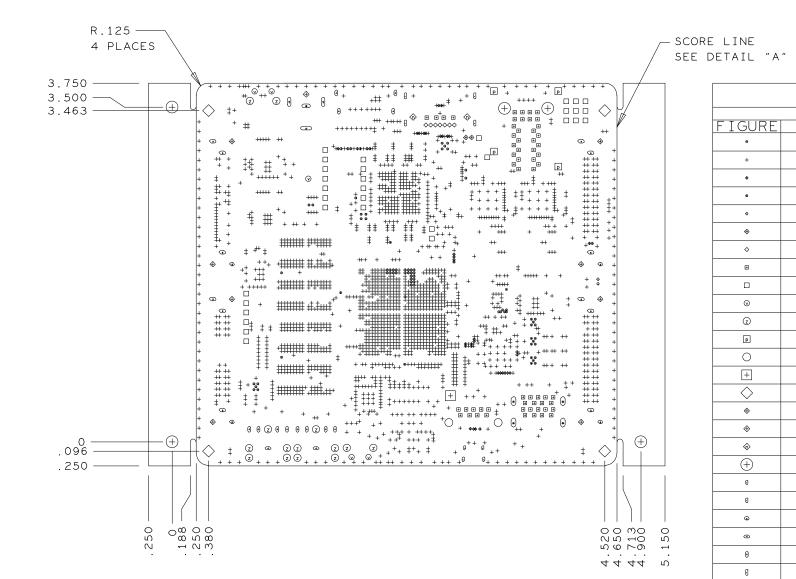
 \square

- ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
- 2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- 3. BOARD MATERIAL SHALL BE 180 Tg/350 Td ISOLA FR-370HR OR EQUIVALENT, Rohs COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- 4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
- 5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
- 6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- 7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- 8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- 9. FOR BACKDRILL INFO. SEE GERBER FILE (BACKDRILL_12-4.ART).

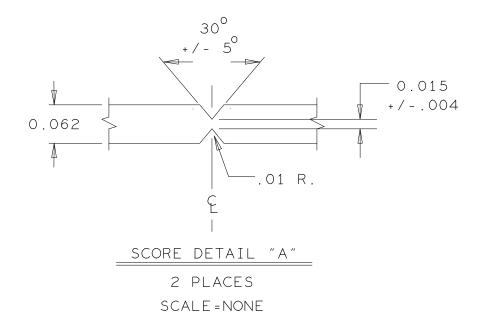
FINISHED AS SMOOTH WALL BY VENDOR. PROCESS NOTES:

- 1. PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 150 MICROINCHES THK MIN GOLD 5-15 MICROINCHES THK MIN.
- 2. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: BLACK. SOLDERMASK SHALL CONFIRM TO IPC-SM-840. CLASS H. CURRENT REV.
- 3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS.
 FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT
 SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
- 4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: ORANGE.

LAYER STACK-UP ALL DIMENSIONS IN MILS		500hm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	90ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%	1000hm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (OZ)	TRACE WIDTH	TRACE WIDTH / SPACE	TRACE WIDTH / SPACE
LAYER 1 - PRIMARY SIDE - SIGNAL	HALF+PLATING	4.72	5.00/9.00	4.00/10.00
LAYER 2 - GROUND PLANE	1			
LAYER 3 - INT. SIGNAL	1	3.70	4.50/10.00	3.70/12.00
LAYER 4 - GROUND PLANE	1			
LAYER 5 - INT. SIGNAL	1	3.70	2 50/10 00	3.70/12.00
LAYER 6 - POWER PLANE	1			
LAYER 7 - POWER PLANE	1			
LAYER 8 - INT. SIGNAL	1	3.70	4-50/10-00	3 /0/12 00
LAYER 9 - GROUND PLANE	1			
LAYER 10- INT. SIGNAL	1	3.70	4.50/10.00	3.70/12.00
LAYER 11- GROUND PLANE	1			
LAYER 12- SECONDARY SIDE - SIGNAL	HALF+PLATING	4.72	5.00/9.00	4.00/10.00



	DRILL CHA	ART: TOP to BOT		
	ALL UN	ITS ARE IN MIL		
FIGURE	SIZE	TOLERANCE	PLATED	QTY
0	6.0	+3.0/-3.0	PLATED	7
+	8.0	+3.0/-3.0	PLATED	2522
•	8.0	+3.0/-3.0	PLATED	67
٥	12.0	+3.0/-3.0	PLATED	39
*	20.0	+3.0/-3.0	PLATED	2
*	26.0	+3.0/-3.0	PLATED	2
♦	31.0	+3.0/-3.0	PLATED	7
	36.0	+3.0/-3.0	PLATED	59
	38.0	+3.0/-3.0	PLATED	32
⊚	40.0	+3.0/-3.0	PLATED	5
2	52.0	+3.0/-3.0	PLATED	14
р	67.0	+3.0/-3.0	PLATED	4
0	91.0	+3.0/-3.0	PLATED	2
+	102.0	+3.0/-3.0	PLATED	1
\Diamond	125.0	+3.0/-3.0	PLATED	4
*	45.0	+3.0/-3.0	NON-PLATED	8
*	63.0	+5.0/-5.0	NON-PLATED	1
•	67.0	+5.0/-5.0	NON-PLATED	2
+	125.0	+5.0/-5.0	NON-PLATED	5
9	41.34x25.59	+4.0/-4.0	PLATED	2
9	47.24x25.59	+4.0/-4.0	PLATED	
•	47.24x39.37	+3.0/-3.0	PLATED	4
Ф	59.0x31.0	+3.0/-3.0	PLATED	2
Θ	59.0x31.0	+3.0/-3.0	PLATED	12
0	63.0x25.0	+3.0/-3.0	PLATED	4
•	70.87x39.37	+3.0/-3.0	PLATED	12
•	90.0x40.0	+3.0/-3.0	PLATED	1
•	93.0x50.0	+3.0/-3.0	PLATED	4
(5)	98.0x40.0	+3.0/-3.0	PLATED	2
•	118.0x40.0	+3.0/-3.0	PLATED	1



TOLERANCES UNLESS	0 g S S O F S	Texas Instruments, I Catalog Processor Business Unit 12500 TI Blvd Dallas, TX 75243	Inc. Texas Instrumen			
OTHERWISE SPECIFIED X.XX ± 0.01 X.XXX ± 0.005 ANGLES ± 1/2°	catal roce	AM572x General Purpose EVM Processor Module FABRICATION DRAWING Size Document Number Modified By: Rev D TI AM572X PM REVA2.BRD TI Applications A2				
DO NOT SCALE DRAWING	ОП	Date: 07/01/2015	Sheet: 1 of 1			

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